25K981, 25K981A

Silicon N-channel Power F-MOS FET

■ Features

- Low ON resistance R_{DS} (on) : R_{DS} (on) = 2.0 Ω (typ.)
- High switching rate : t_f = 40ns (typ.)
- No secondary breakdown
- High breakdown voltage

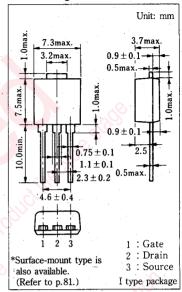
■ Application

- No contact relay
- · Solenoid drive
- · Motor drive
- Control equipment
- Switching power source

■ Absolute Maximum Ratings (Tc=25°C)

Item		Symbol	Value	Unit	
Drain-source voltage	2SK981	V	400	V	
Drain-source voltage	2SK981A	V _{DSS}	450	V	
Gate-source voltage	V _{GSS}	±20	V		
Drain current	DC	I _D	3	A	
	Peak-to-peak value	I_{DP}	6		
Power dissipation	Tc=25℃	D.	15	W	
	Ta=25℃	P_{D}	1.3) (V)	
Channel temperature			c		
Storage temperature	T_{stg}	$-55 \sim +150$	S.		

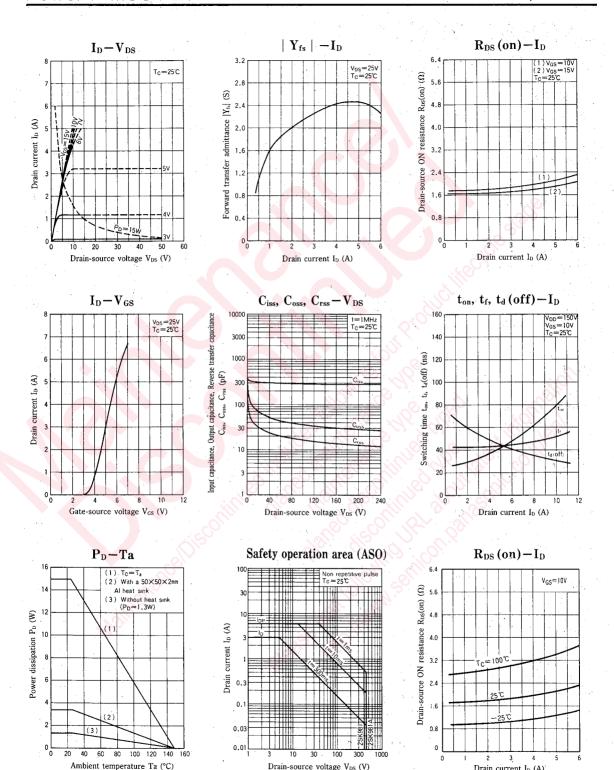
■ Package Dimensions



■ Electrical Characteristics (Tc=25°C)

Item		Symbol	Condition	min.	typ.	max.	Unit
Drain current		I _{DSS}	$V_{DS} = 320V, V_{GS} = 0$	-W.		0.1	mA
Gate-source current	-(e)	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0$	NO		±1	μA
Drain-source voltage	2SK981	V _{DSS}	$I_D = 1 \text{ mA}, V_{GS} = 0$	400			v
	2SK981A			450			V
Gate threshold voltage		V _{th}	$V_{DS}=25V$, $I_D=1mA$	1		5	V
Drain-source ON resist	ance	R _{DS} (on)	$V_{GS} = 10V, I_D = 2A$		2.0	3.0	Ω
Forward transfer admit	tance	Yfs	$V_{DS}=25V$, $I_D=2A$	1.2	2.0		S
Input capacitance		Ciss	$V_{DS} = 20V, V_{GS} = 0, f = 1MHz$		310		pF
Output capacitance		Coss			75		pF
Reverse transfer capacitance		Crss	· ·		35		pF
Turn-on time		ton	$V_{GS}=10V$, $I_D=2A$		30		ns
Fall time		t _f			40		ns
Delay time		td(off)	$V_{DD} = 150 \text{V}, R_L = 75 \Omega$		60		ns

Drain current ID (A)



Drain-source voltage VDS (V)

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